12:30: Philowave

Presenter: Mohammad Abu Khater, Founder-CEO

Mohammad received his PhD from Purdue University. His technical focus is on adaptive wireless frontends, and he is a Senior Member of the IEEE. He is the founder and CEO of Philowave, a company specializing in spectrum sensing and adaptive wireless devices.

12:40: JITX

Presenter: Duncan Haldane CEO at JITX

Duncan started working on JITX because he wanted a better way to design robots. While he was at Berkeley he started collaborating with Jonathan on better design tools for origami robots. Duncan's work in robotics won him a best-paper award from the IEEE International Conference on Intelligent Robots and Systems and a Guinness World Record.

12:50: INCIRT GmbH

Presenter: Theodore Varelas, SVP of Business Development, INCIT

Theodore Varelas is the SVP of Business Development at INCIT. He is a semiconductor industry executive with a proven track record in driving innovation and market growth across emerging technology domains.

He has previously worked at Infineon Technologies, where he held key roles in product and strategic marketing within the automotive and security controller business lines. He was responsible for positioning Infineon's embedded controller solutions across multiple vertical markets, including IoT nodes and networks, computing, and automotive applications.

Before joining Infineon in 2012, he held various business development and general management positions across the semiconductor sector. Theodore Varelas is an INSEAD alumnus and holds a Master of Engineering degree from Carleton University in Ottawa, Canada, and a Diploma in Engineering from the University of Patras, Greece.

13:00: Flexiramics

Presenter: Andy Wynn, CEO , Flexiramics

Andy Wynn is CEO of Flexiramics and a seasoned technology leader with over 30 years of experience bringing advanced materials from innovation to large-scale commercial adoption in global industrial and high-tech markets. A former CTO of Morgan Advanced Materials plc, a FTSE 250 multinational, he has led the commercialization of more than $2 billion in new technology sales, including materials solutions for the semiconductor, electronics, and high-performance computing sectors. Andy combines deep expertise in materials science with a strong track record of scaling manufacturing, building global partnerships, and aligning innovation with market needs. At Flexiramics, he is leading the introduction of the world's first flexible ceramic platform, enabling next-generation electronics with significantly improved thermal performance and reduced signal loss for high-frequency and AI-driven applications.

13:10: EchoICs

Presenter: Dr. Thomas Tapen - Co-Founder & CEO EchoICs Inc.

Thomas Tapen (B.S. ‘15, Ph.D. ‘21 Cornell University) is co-founder and CEO of EchoICs Inc, an RFIC startup commercializing advanced widely tunable RF frontend components. He has over 10 years experience in RF, analog, and mixed-signal circuit design with a focus on wideband and widely tunable RF techniques. His research has been published in Nature and multiple IEEE journals, and he received the Outstanding Ph.D. Thesis Award from the Cornell Electrical and Computer Engineering department in 2021 for his Ph.D. research.

13:20: Jones Microwave Inc.

Presenter: Thomas Jones, PhD, CEO of Jones Microwave Inc.

Dr. Thomas R. Jones is the founder of Jones Microwave Inc., an Alberta-based spinout from the University of Alberta and Purdue University, commercializing IP-protected cutting-edge microwave to sub-THz technologies for telecommunications, instrumentation, aerospace, and defence.

He holds a Ph.D. in electrical and computer engineering from the University of Alberta and previously served as a research scientist at Purdue University. His career includes research and engineering roles across academia and industry, including an NSERC Postdoctoral Fellowship at Purdue.

Dr. Jones's expertise spans high-frequency, high-power, and high-speed microwave, millimeter-wave, and sub-THz systems, including reconfigurable RF front ends and on-chip device fabrication. He has authored work with over 500 citations, holds four patents, and has raised over five million dollars in funding for his company. His awards include the 2023 Douglas R. Colton Medal for Research Excellence and multiple national scholarships. He actively contributes to IEEE, currently serving as MTT-S MGA Regional Coordinator for R7 Canada.

13:30: TransEON

Presenter: Vallen Rezazadeh, Founder and CEO

Vallen Rezazadeh is the founder and CEO of TransEON Inc., a Canadian startup developing next-gen GaN device and process technology for applications across the RF spectrum. Prior to TransEON, he was with IBM Research at the CNSE/Albany NanoTech development fab in Albany, NY, USA, where he oversaw electrical test operations for MRAM and advanced CMOS nodes, collaborating with various industry partners including Samsung, GlobalFoundries, and Applied Materials. Vallen received the B.Sc. degree in engineering physics and the M.Sc. degree in electrical engineering with a specialization in solid-state electronics from the University of Alberta.